

Abstract of Japanese Patent Office Gazette

No. S60-195957

LEAD FRAME

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Filed: Mar. 19, 1984
Disclosed: Oct. 4, 1985

PURPOSE: To improve the contacting property between a lead frame and a resin and to enhance the sealability and the reliability by stepwisely forming the side of the lead frame, and increasing the contacting surface with the resin.

CONSTITUTION: Projections 8, 15 are formed on tabs 4, 13 of a lead frame, tab hanging lead 5 and the sides of leads 6, 14. The projection 8 is formed by a suitable method. The lead frame 12 is, for example, composed of 42-alloy. A semiconductor chip 9 is formed, for example, of silicon single crystal substrate, many circuit elements are formed in the chip by the know technique, and one circuit function is formed. A resin sealer 11 is formed, for example, of epoxy resin, and molded by a known transfer molding method.